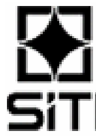

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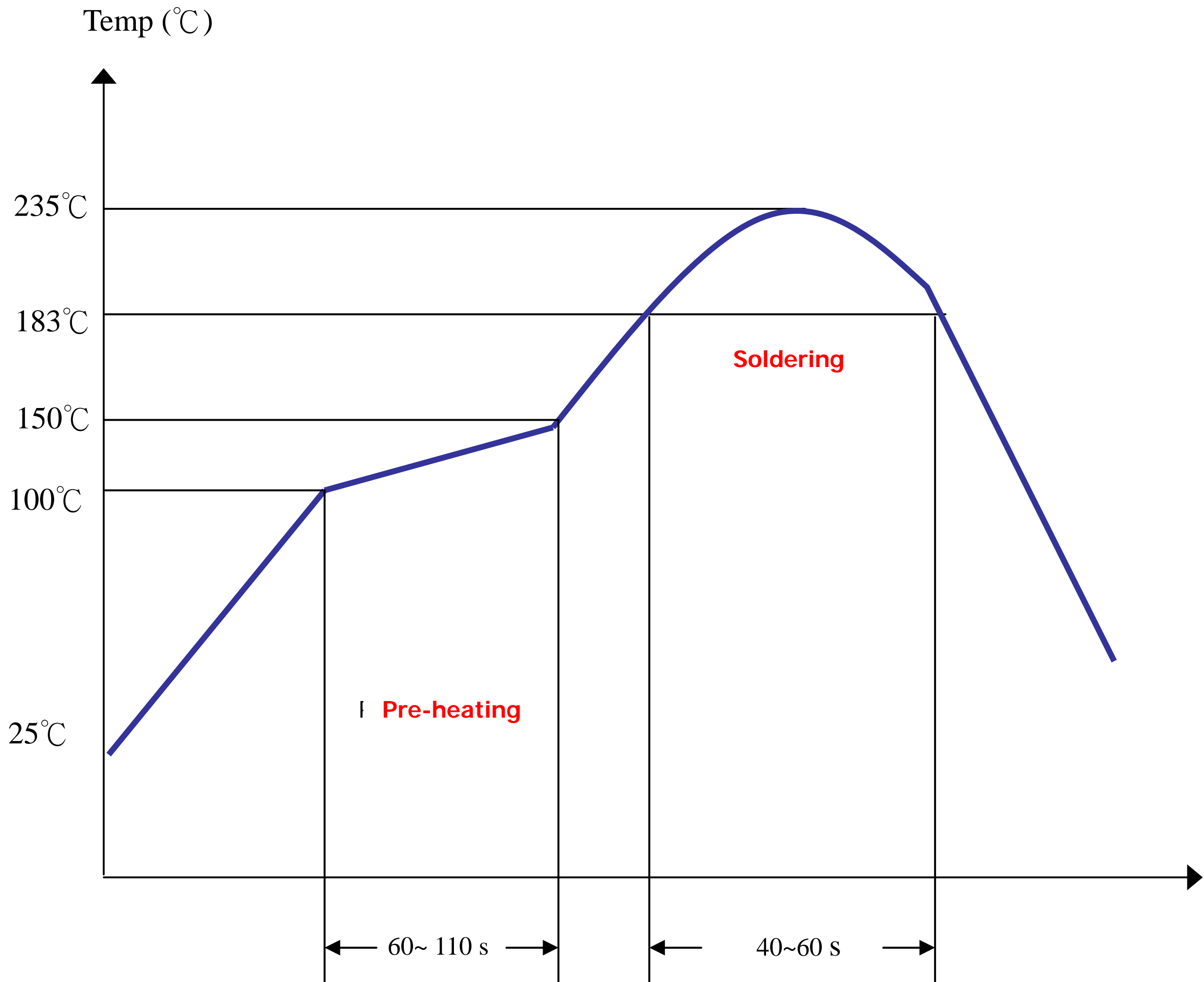
Reflow Profiles for ICs with Sn-Pb eutectic assembly



Testing Content:

Stage	Condition	Duration
1'st Ram Up	3.0+/-2℃/sec	
Preheat	100℃~150℃	60~110 secs
2'nd Ram Up	2.0+/-1℃/sec	
Solder Joint	183℃ above	60~90 secs
Peak Temp	235+5/-0℃	5 secs
Rpmp Down rate	-6℃/sec max	